

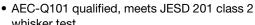
Hyperfast Rectifier, 30 A FRED Pt®



PRODUCT SUMMARY					
Package	TO-247AD 3L				
I _{F(AV)}	30 A				
V_{R}	600 V				
V _F at I _F	1.4 V				
t _{rr} typ.	26 ns				
T _J max.	175 °C				
Diode variation	Single die				

FEATURES

- Low forward voltage drop
- Hyperfast soft recovery time
- 175 °C operating junction temperature
- Designed and qualified according to commercial qualification









ROHS COMPLIANT HALOGEN

DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V _{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 112 °C	30				
Non-repetitive peak surge current	I _{FSM}	T_C = 25 °C, t_p = 8.3 ms half sine wave; connecting two anode pins	240	А			
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-		
Forward voltage	V _F	I _F = 30 A	-	2.0	2.65	V	
		I _F = 30 A, T _J = 150 °C	-	1.4	1.8		
D l . l	,	$V_R = V_R$ rated	-	0.02	30		
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	300	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ	





DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	26	-		
Reverse recovery time	t _{rr}	T _J = 25 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	26	-	ns - A	
		T _J = 125 °C		-	70	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	3.5	-		
		T _J = 125 °C		-	7.6	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	50	-	200	
		T _J = 125 °C		-	280	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to case	R _{thJC}		-	0.7	1.1	°C/W
Thermal resistance, junction to ambient per leg	R _{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heat sink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	5.5	-	g
Weight			-	0.2	-	OZ.
Mounting torque			1.2 (10)	-	2.4 (20)	kgf · cm (lbf · in)
Marking device		Case style TO-247AD 3L		APH3	006LH	•

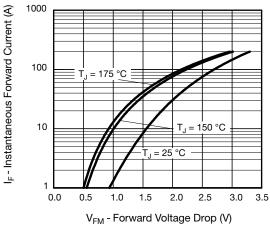


Fig. 1 - Typical Forward Voltage Drop Characteristics

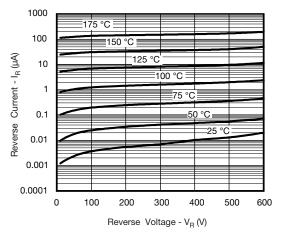


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

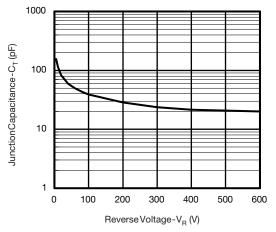


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

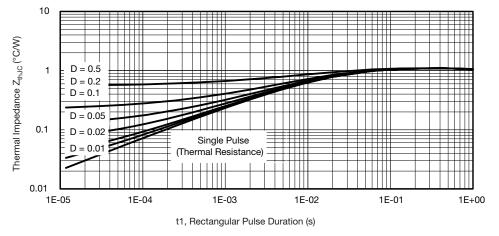


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

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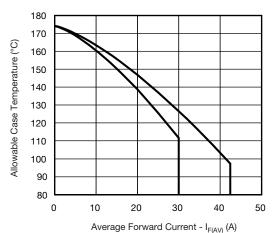


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

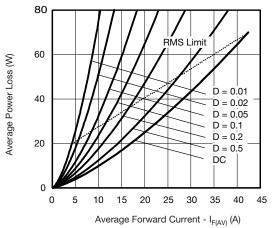


Fig. 6 - Forward Power Loss Characteristics

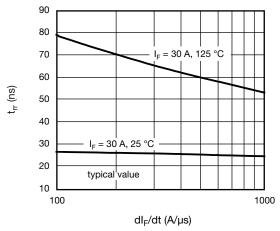


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

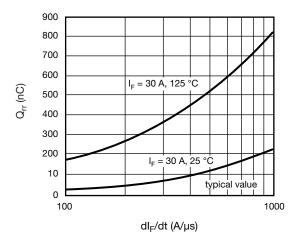
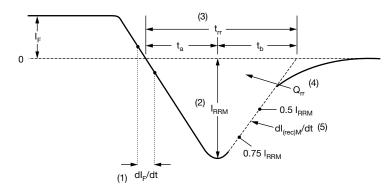


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

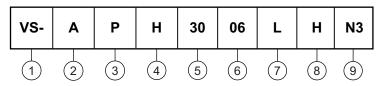
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 Circuit configuration:

A = single diode

- **3** P = TO-247
- 4 H = hyperfast recovery time
- 5 Current code (30 = 30 A)
- 6 Voltage code (06 = 600 V)
- 7 L = long lead
- 8 H = AEC-Q101 qualified
- 9 Environmental digit:

N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

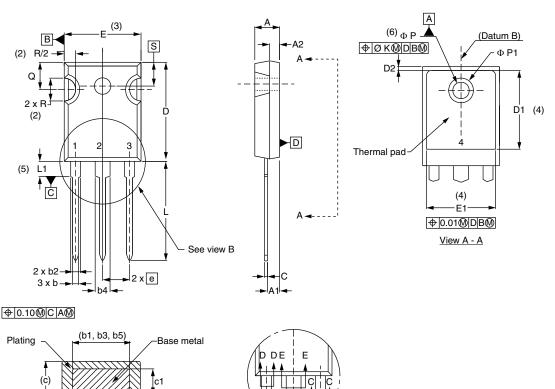
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-APH3006LHN3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AD 3L	www.vishay.com/doc?95626			
Part marking information	TO-247AD 3L	www.vishay.com/doc?95007			



TO-247AD 3L

DIMENSIONS in millimeters and inches



(4) Section C - C, D - D, E - E							
SYMBOL	MILLIN	IETERS	INC	HES	NOTES		
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.65	5.31	0.183	0.209			
A1	2.21	2.59	0.087	0.102			
A2	1.50	2.49	0.059	0.098			
b	0.99	1.40	0.039	0.055			

0.039

0.065

0.065

0.102

0.102

0.015

0.015

0.776

0.515

0.053

0.094

0.092

0.135

0.133

0.035

0.033

0.815

(h h2 h4)

:5	

View B

SYMBOL	IVIILLIIV	ILILING	INCLIES		NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46 BSC		0.215	BSC	
ØΚ	0.2	0.254		0.010	
L	19.81	20.32	0.780	0.800	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		
•	•		•		•

INCHES

MILLIMETERS

Notes

b1

b2

b3

b4

b5

С

с1

D

D1

(1) Dimensioning and tolerancing per ASME Y14.5M-1994

1.35

2.39

2.34

3.43

3.38

0.89

0.84

20.70

- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body

3

- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1

0.99

1.65

1.65

2.59

2.59

0.38

0.38

19.71

13.08

- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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